

Global Adhesive Paste and Film Market in Semiconductor Packaging Industry 2012-2017: Trends, Forecast, and Opportunity Analysis, February 2013

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Abstracts

The global adhesive paste and film market for semiconductor packaging industry is on the threshold of significant growth. Asia was the top continent in terms of total adhesive paste and film manufacturing and consumption; however, North America and Europe saw the highest growth rate because of rapidly increasing demand in developed economies and increasing demand for semiconductor devices. According to market forecasts, the global adhesive paste and film market is poised for growth at 5.9% CAGR over the next five years to reach \$1.3 billion in 2017.

Lucintel, a leading global management consulting and market research firm, has conducted a competitive analysis on this market and presents its findings in "Global Adhesive Paste and Film Market in Semiconductor Packaging Industry 2012-2017: Trends, Forecast, and Opportunity Analysis ." This study provides a concise overview of the global adhesive paste and film market in terms of value and opportunities for growth. This sophisticated and capital-intensive market requires a range of highly advanced technologies.

Lucintel discusses the various challenges and opportunities faced by the global adhesive paste and film market. One major challenge is the increased price of resins and other raw materials. Adhesive pastes and films are used for three basic applications in the semiconductor devices: dicing, back-grinding, and die-attach. These days, devices with both analog and digital components are manufactured.

Lucintel's study encompasses the industry's major drivers. Innovation and capital are

the most significant drivers for the semiconductor packaging industry. Manufacturing semiconductor devices require enormous capital investments and a highly skilled workforce. Major manufacturers are investing in extensive R&D for developing more innovative products. Thinner devices are now manufactured for enhancing device performance and in turn, increase the demand for adhesive paste and films.

This report highlights different aspects of the global adhesive paste and film market. Due diligence has been given to the current market scenario, technological, and monetary benefits of manufacturing adhesive pastes and films globally. Asia is the leader in both manufacturing and consuming adhesive pastes and films.

This unique report from Lucintel will provide you with valuable information, insights, and tools needed to identify new growth opportunities and operate your business successfully in this market. This report will save hundreds of hours of your own personal research time and will significantly benefit you in expanding your business in this market. In today's stringent economy, you need every advantage that you can find.

To make business, investment, and strategic decisions, you need timely, useful information. This market report fulfills this core need and is an indispensable reference guide for multinational materials suppliers, product manufacturers, investors, executives, distributors, and many more that operate in this market.

Some of the features of "Global Adhesive Paste and Film Market in Semiconductor Packaging Industry 2012-2017: Trends, Forecast, and Opportunity Analysis" include:

- Porter's Five Forces analysis for global adhesive paste and film market in semiconductor packaging industry

- Global thin film adhesive paste and film market in semiconductor packaging industry size by region and by application in terms of value and volume

- Drivers and challenges for global adhesive paste and film market in semiconductor packaging industry

- Regional analysis of the global adhesive paste and film market in semiconductor packaging industry by the key regions of North America, Europe, Asia Pacific, and Rest of the World in terms of value and volume

Global adhesive paste and film market in semiconductor packaging industry trend (2006-2011) & forecast (2012-2017) by region and by application in terms of value and volume

Growth opportunities and emerging trends in global adhesive paste and film market in semiconductor packaging industry

More than 55 figures/charts and 16 tables are provided in this roughly 107page report

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